



Memory Module Specifications

NTBSD4P32SP-08

8GB (1Rx8 1G x 64-Bit/2R8 512M x 64Bit) PC4-3200
CL16 288-Pin DIMM

DESCRIPTION

NTBSD4P32SP-08 is a 1G x 64-bit (1R8) or 512M x 64-bit (2R8) SDRAM (Synchronous DRAM), memory module based on eight 1G x 8-bit or sixteen 512M x 8 FBGA components per module. The SPD is programmed to latency timing of 16-20-20 at 1.35V. support XMP, Each 288-pin DIMM uses gold contact fingers. The electrical and mechanical specifications are as follows:

FEATURES

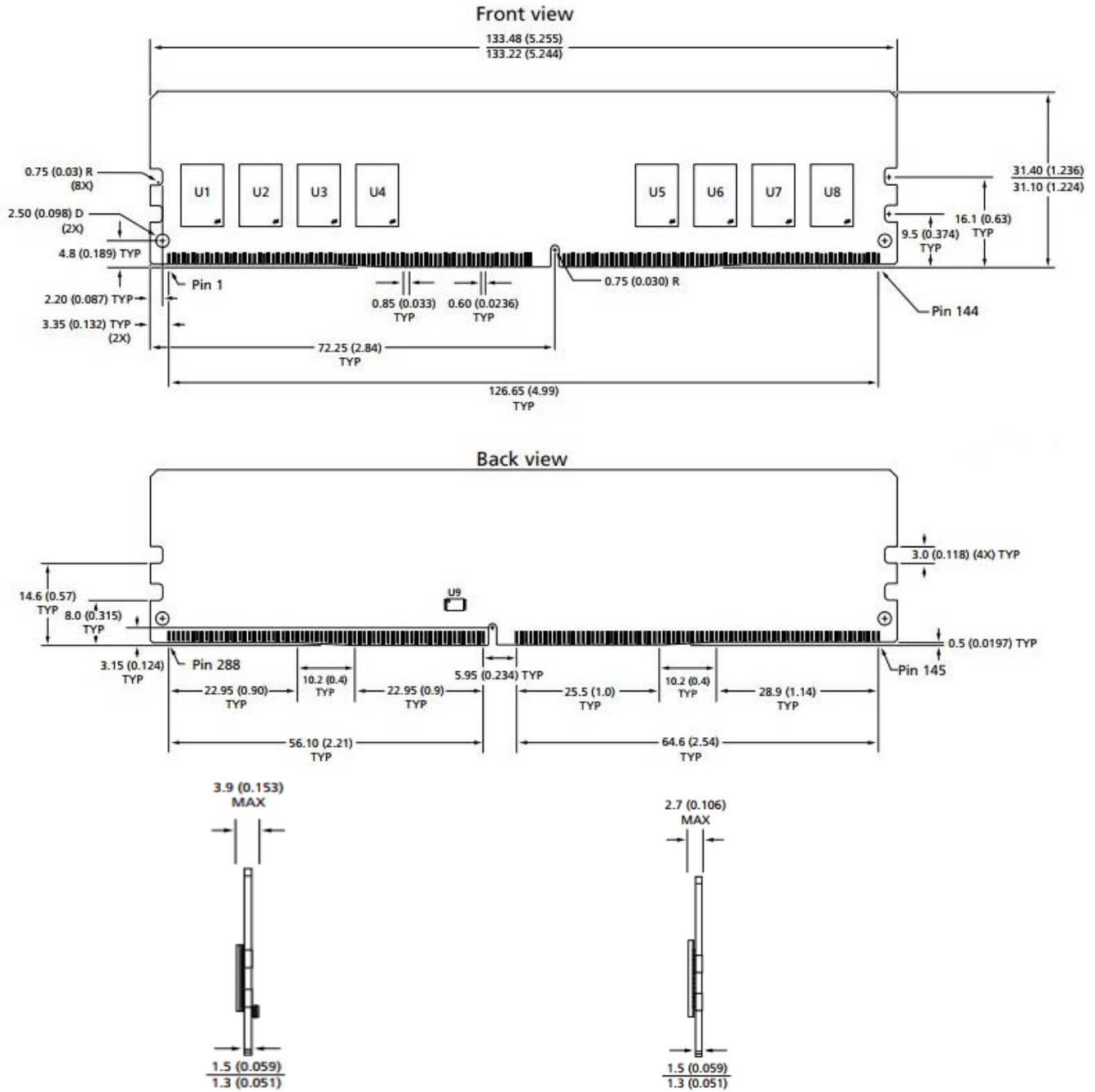
- Power Supply: VDD=1.35V Typical
- VDDQ = 1.2V Typical
- VPP - 2.5V Typical
- VDDSPD=2.2V to 3.6V
- Nominal and dynamic on-die termination (ODT) for data, strobe, and mask signals
- Low-power auto self refresh (LPASR)
- Data bus inversion (DBI) for data bus
- On-die VREFDQ generation and calibration
- Single-rank
- On-board I2 serial presence-detect (SPD) EEPROM
- 16 internal banks; 4 groups of 4 banks each
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the mode register set (MRS)
- Selectable BC4 or BL8 on-the-fly (OTF)
- Fly-by topology
- Terminated control command and address bus
- PCB: Height 1.23" (31.25mm)
- RoHS Compliant and Halogen-Free

SPECIFICATIONS

CL(IDD)	16 cycles
Row Cycle Time (tRCmin)	45ns(min.)
Refresh to Active/Refresh	350ns(min.)
Command Time (tRFCmin)	
Row Active Time (tRASmin)	26.25ns(min.)
Maximum Operating Power	TBD W*
UL Rating	94V-0
Operating Temperature	0° C to +70° C
Storage Temperature	-40° C to +85° C

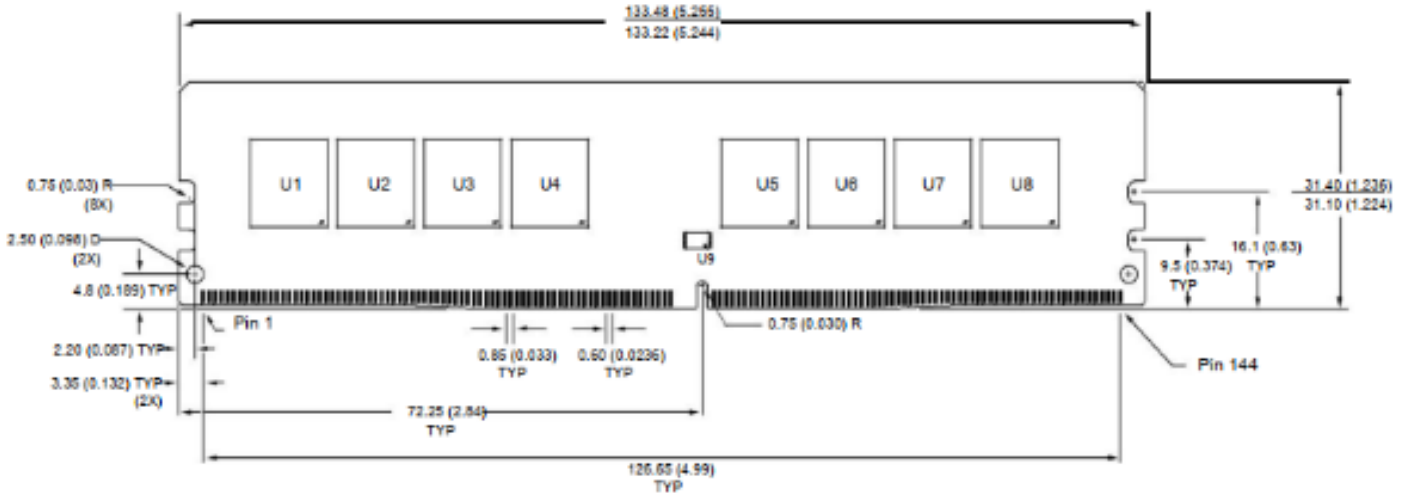
*Power will vary depending on the SDRAM used.

MODULE DIMENSIONS

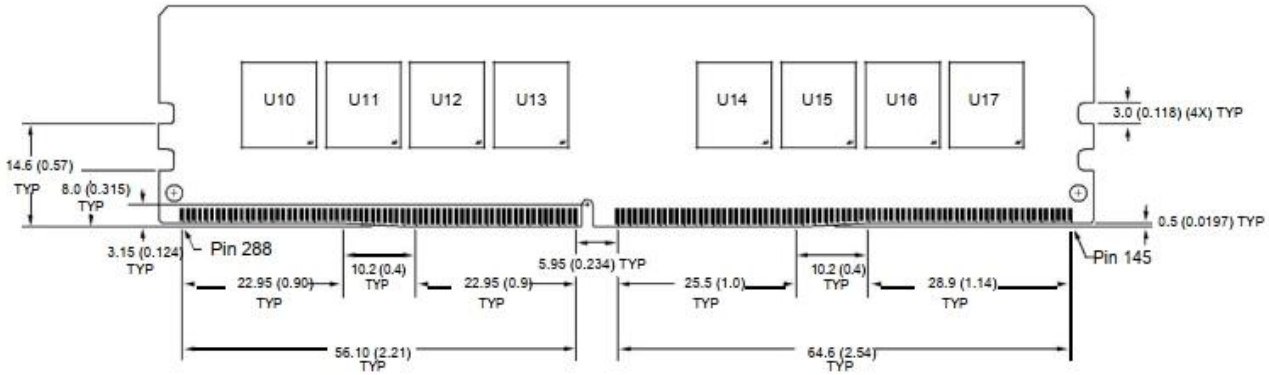


※The location of U9 may be on the front or on the back, Above Picture is for reference only!

Front view



Back view



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